

# **Preliminary User's Manual**

AB-065PI-64GK, AB-065PI-80GC, AB-065PI-100GF

**Application Boards AB-065PI** 

**Hardware** 

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#### **Preface**

Readers This manual is intended for users who want to understand the functions of the

AB-065PI Application Boards.

Purpose This manual presents the hardware manual of the AB-065PI Application

Boards.

**Organization** This system specification describes the following sections:

• Hardware overview

Hardware installation

• Measurement/debug possibility

• Electrical characteristics of the development board

• Electrical target specification of prototype chip

**Legend** Symbols and notation are used as follows:

Weight in data notation: Left is high-order column, right is low order column

Active low notation : n (small letter n before or after signal name)

Memory map address: : High order at high stage and low order at low stage

Note : Explanation of (Note) in the text

Caution : Item deserving extra attention

**Remark** : Supplementary explanation to the text

Numeric notation : Binary . . . xxxx or xxx<sub>b</sub>

Decimal . . . xxxx<sub>d</sub>

Hexadecimal . . . xxxxH or 0x xxxx

Prefixes representing powers of 2 (address space, memory capacity)

K (kilo):  $2^{10} = 1024$ 

M (mega):  $2^{20} = 1024^2 = 1.048.576$ G (giga):  $2^{30} = 1024^3 = 1.073.741.824$ 

Data Type: Word ... 32 bits

Halfword ... 16 bits

Byte ... 8 bits

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## **Chapter 1** Introduction

The Application Board AB-065PI is the common solution for the user's target hardware for quick functional tests and experimental applications of the NEC real chip microcontrollers and its development tools (emulators). It connects the device or tool with the clock signal, reset circuit, power supply and interface connectors.

The pin assignment for these connections and the additional user's circuits are free definable by the user, due to the own specification and type of the used microcontroller.

The connection to the real device or tool is realized with the NQPACK-type socket. Depending of the pin number and the footprint three different configurations of the AB-065PI are available:

- AB-065PI-64GK (equipped with NQPACK064SB)
- AB-065PI-80GC (equipped with NQPACK080SB)
- AB-065PI-100GF (equipped with NQPACK100RB)

To the delivery area belongs also the corresponding HQPACK-type socket for the real chip and the YQPACK-type socket for the emulation probe.

#### 1.1 Features:

- · prepared power supply connections
- · adapted to the typical 0.65 mm pitch devices
- · real chip or emulator sockets available
- reset circuit with power-up reset and reset button
- · oscillator socket on board
- 8 x multi-SOT-footprint for user's applications
- individual pins prepared for pull-up and pull-down resistors
- DIL-SMD-area for user's applications
- assembled typical interface connectors
- board size: 270 mm x 140 mm

## **Chapter 2** General Remarks

## 2.1 Terminology

Table 2-1: Terminology

Term	Description
Real device	Microcontroller IC, one-chip microcomputer with integrated periphery
Emulator	Development tool consisting of hardware and software for functional reproduction of the real device
Target hardware	hardware connected to the real chip or to emulator, electrical environment of the microcontroller

## **Chapter 3** Outlook of the Application Board

The outlook of the Application Board AB-065PI shows the Figure 3-1.

Power supply & ground connectors

Oscillator socket & reset-button

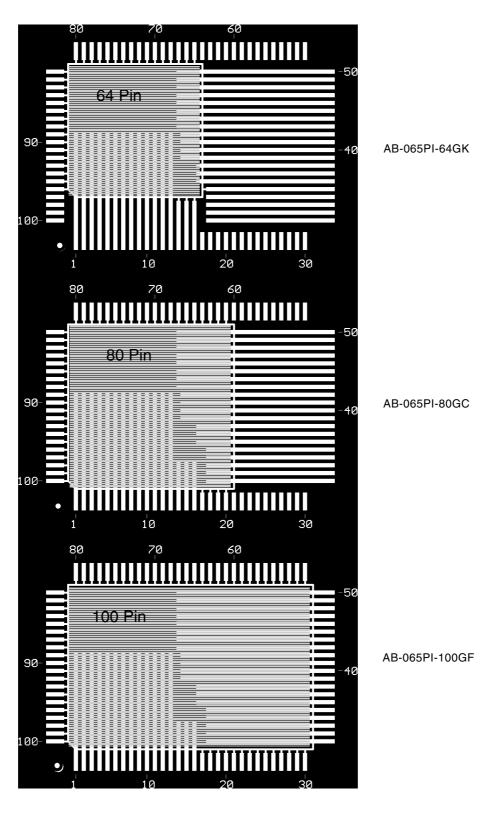
Multi-QFP-footprint
Individual pin connections
Multi-SOT-footprint
DIL SMD area
Wrap field
Interface connectors

Figure 3-1: Outlook of the Application Board AB-065PI

## Chapter 4 Multi-QFP-Footprint

The Figure 4-1 shows the connector footprints corresponding to the configuration of the AB-065PI.

Figure 4-1: Types of the NQPACK connectors assembled on the AB-065PI Application Board



Note: Pin 1 marked with O.

The allocation of the device pins on the AB-065PI depends of the board configuration:

Table 4-1: Pin assignment on the multi-QFP-footprint (1/2)

Board pins Socket p		Socket pins	
	100GF	80GC	64GK
1	1	1	1
2	2	2	2
3	3	3	3
4	4	4	4
5	5	5	5
6	6	6	6
7	7	7	7
8	8	8	8
9	9	9	9
10	10	10	10
11	11	11	11
12	12	12	12
13	13	13	13
14	14	14	14
15	15	15	15
16	16	16	16
17	17	17	-
18	18	18	-
19	19	19	17
20	20	20	-
21	21	-	-
22	22	-	-
23	23	-	-
24	24	-	-
25	25	-	-
26	26	-	-
27	27	-	-
28	28	-	-
29	29	-	-
30	30	-	-
31	31	21	-
32	32	22	-
33	33	23	-
34	34	24	-
35	35	25	-
36	36	26	18
37	37	27	19
38	38	28	20
39	39	29	21
40	40	30	22

Board pins	Socket pins			
	100GF	80GC	64GK	
41	41	31	23	
42	42	32	24	
43	43	33	25	
44	44	34	26	
45	45	35	27	
46	46	36	28	
47	47	37	29	
48	48	38	30	
49	49	39	31	
50	50	40	32	
51	51	-	-	
52	52	-	-	
53	53	-	-	
54	54	-	-	
55	55	-	-	
56	56	-	-	
57	57	-	-	
58	58	-	-	
59	59	-	-	
60	60	-	-	
61	61	41	-	
62	62	42	-	
63	63	43	•	
64	64	44	-	
65	65	45	33	
66	66	46	34	
67	67	47	35	
68	68	48	36	
69	69	49	37	
70	70	50	38	
71	71	51	39	
72	72	52	40	
73	73	53	41	
74	74	54	42	
75	75	55	43	
76	76	56	44	
77	77	57	45	
78	78	58	46	
79	79	59	47	
80	80	60	48	

## Chapter 4 Multi-QFP-Footprint

Table 4-1: Pin assignment on the multi-QFP-footprint (2/2)

Board pins	Socket pins		
	100GF	80GC	64GK
81	81	61	49
82	82	62	50
83	83	63	51
84	84	64	52
85	85	65	53
86	86	66	54
87	87	67	55
88	88	68	56
89	89	69	57
90	90	70	58

Board pins	Socket pins		
	100GF	80GC	64GK
91	91	71	59
92	92	72	60
93	93	73	61
94	94	74	62
95	95	75	63
96	96	76	64
97	97	77	-
98	98	78	-
99	99	79	-
100	100	80	-

## **Chapter 5** Individual Pin Connections

This layout offers a high degree of flexibility (Figure 5-1):

- (1) Pull-up: either SMD or wired component e.g. resistor, DIL-Switches and -Arrays, LEDs etc.
- (2) Pull-Down: either SMD or wired component e.g. resistor, DIL-Switches and -Arrays, LED, capacitor
- (3) Additional connection for measurement or routing to wire-wrap area
- (4) Default  $V_{CC}$ -connection User may cut this and establish  $LV_{DD}$ -connection

By combining multiple assembly-options, even more complex options are possible.

4 1 2 2 To socket-pin GND

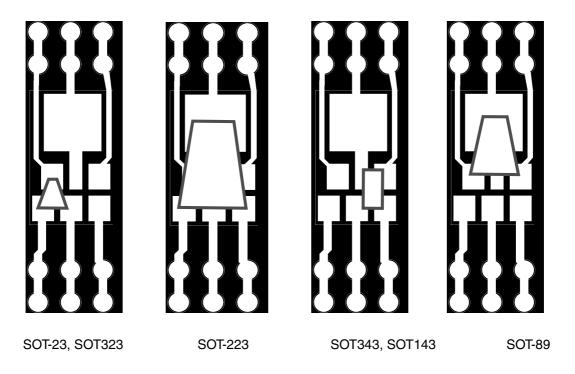
Figure 5-1: Individual pin connections

## **Chapter 6 Multi-SOT-Footprint**

This pattern is designed to accept various different SMD-packages for user's own active components: transistors, buffers, one-gate ICs etc.

Following placements are suggested:

Figure 6-1: Assembly samples on the multi-SOT-footprint



## Chapter 7 DIL-SMD-area

This combined area can be used to assemble DIL-IC's in a conventional wired-package with 0.3 inch and 0.6 inch width.

Also SMD-packages with variable width and 2.54 mm and 1.27 mm Pitch can be assembled.

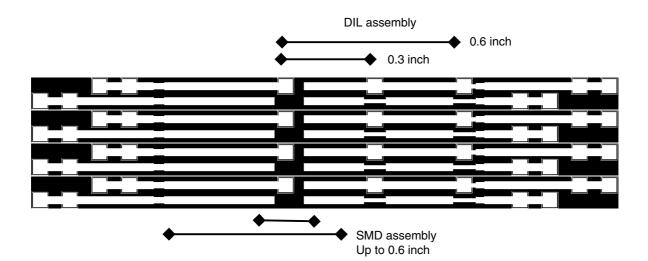


Figure 7-1: DIL-SMD-area

## **Chapter 8 Circuit Diagrams**

The reset circuit and the socket for the quartz oscillator are placed on the Application Board AB-065PI. The other circuits and connections can be specified by the user on the multi-SOT-footprint, individual pin connections, DIL-SMD-area and wrap field.

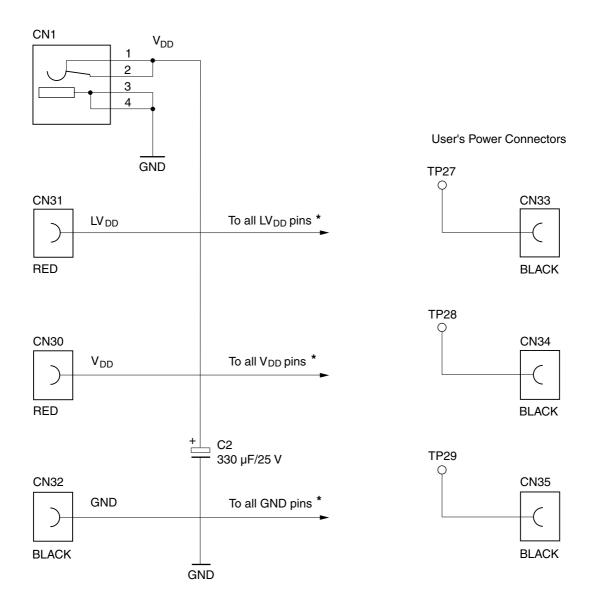
## 8.1 Power supply

The power supply can be connected to the AB-065PI board either to the CN1 (standard power supply) or to the CN30 ( $+V_{DD}$ ) and CN32 (GND). The  $V_{DD}$  net on the AB-065PI board is always connected to both CN1 and CN30. An additional user's voltage can be connected to the CN31 ( $LV_{DD}$ ).

The user's power connectors CN33, CN34, CN35 can be specified by the user. They are not connected with any other nets.

Figure 8-1: Power Supply Circuit

### **Power Connectors**



Note: \*: see Figure 5-1.

## 8.2 Reset circuit

The low-active  $\overline{\text{RESET}}$  signal is available on the TP32 and TP34 (Figure 8-2).

Figure 8-2: Reset circuit

## 8.3 Quartz oscillator

If the quartz oscillator is assembled on the X1 socket, the CLK signal is available on the TP33 (Figure 8-3).

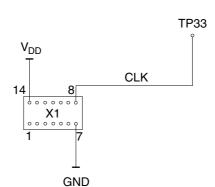


Figure 8-3: Socket for the quartz oscillator

## **Chapter 9** Placement of the Components

Figure 9-1: Placement of the Components



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